



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR POWERPAK® 0806					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
Bond Int	40	20 000	200 °C + N2	0	0.00
HAST	246	24 600	130 °C, 85 % RH	0	0.00
Pressure pot	231	22 176	121 °C, 15 PSIG	0	0.00
Temp. cycle	246	246 000	-55 °C to +150 °C	0	0.00
Solderability	15	15	8 hours	0	0.00